

# QuickSinter<sup>®</sup>

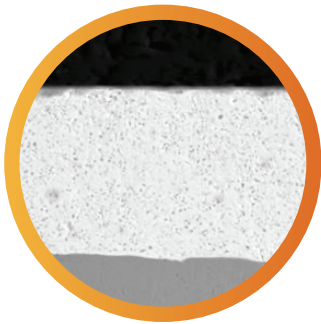
High metal content paste, redefining sinter technology for power electronics



## Pressure Sinter Pastes

### InFORCE<sup>™</sup>

Target applications: Power module die-attach and sintered package attach to cooler

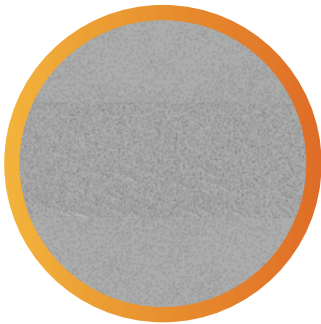
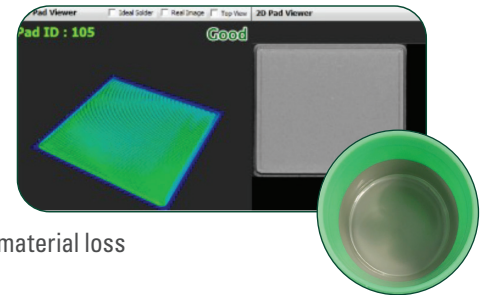


### InFORCE<sup>™</sup> MF

Pressure silver sinter paste for die-attach

**Features:**

- Formulated for printing application. Reduces overprint
- High metal load / low organic content. Fast dry times, less material loss
- Multi finish. Sinters to Ag, Au, or bare Cu
- Suitable for Si IGBT, SiC MOSFET, and GaN HEMT
- Shear strength >50MPa for 5x5 SiC MOSFET



### InFORCE<sup>™</sup> 29

Pressure copper sinter paste

**Features:**

- Workability – Printable or dispensable
- Sinters to Cu, Ag, and Au
- Sinterable under N<sub>2</sub>, vacuum, H<sub>2</sub>, forming gas or formic acid
- Shear strength >50MPa
- High metal load / low organic content



### InFORCE<sup>™</sup> LA

Pressure silver sinter paste for large area sintering/package attach

**Features:**

- Formulated for large area such as sintered package attach
- Drying can be done after component placement (wet process)
- Dispense “print like” film deposits (slot nozzle dispensing)

[indium.com/products/silver-sintering](http://indium.com/products/silver-sintering)



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**From One Engineer To Another<sup>®</sup>**

*All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.*

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